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(71) Applicant (for all designated States except US): **DUPONT CANADA INC.** [CA/CA]; 7070 Mississauga Road, Mississauga, Ontario L5M 2H3 (CA).

(71) Applicant and

(72) Inventor: **BATES, Phil** [CA/CA]; 4560 Davidson Road, RR #1, Inverary, Ontario K0H 1X0 (CA).

(72) Inventors; and

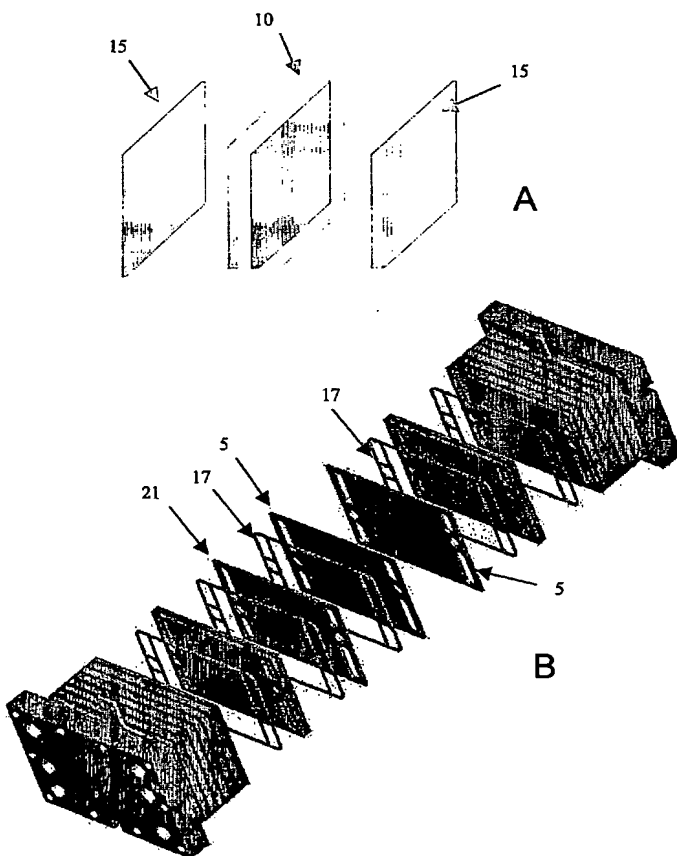
(75) Inventors/Applicants (for US only): **ANDRIN, Peter** [CA/CA]; 34 Sarah Street, Napanee, Ontario K7R 3X4 (CA). **CHOUDHURY, Biswajit** [CA/CA]; 1005 - 175 Bath Road, Kingston, Ontario K7M 7K9 (CA). **EKHATOR, Iyobosa** [CA/CA]; 2 - 335 Division Street, Kingston, Ontario K7K 4A2 (CA). **GHOSH, Kalyan** [IN/CA]; 509 - 247 Bath Road, Kingston, Ontario K7M 2X9 (CA). **WIELAND, Helmut** [CA/CA]; 721 Hillview Road, Kingston, Ontario K7M 5C8 (CA).

(74) Agents: **CLARIZIO, Dino, P.** et al.; Benneth Jones LLP, 3400 1 First Canadian Place, P.O. Box 130, Toronto, Ontario M5X 1A4 (CA).

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(54) Title: PROCESS FOR SEALING PLATES IN AN ELECTROCHEMICAL CELL\_\_\_\_\_



(57) Abstract: There is provided a process for sealing a coolant plate to an adjacent bi-polar plate or coolant plate in an electrochemical cell. The first coolant plate comprises at least one mating region for mating with a complementary region on the adjacent plate, the adjacent plate is a second coolant plate or a bipolar plate of the electrochemical cell, and the first coolant plate and the adjacent plate each comprise a polymer and conductive filler. The process comprises the step of welding the mating region to the complementary region to create a seal formed by the polymer at the mating region and the complementary region. Welding may be done using resistance welding or vibration welding processes.

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